

FLO SERIES

PART NUMBER: SA-EL-FLB

Buffers

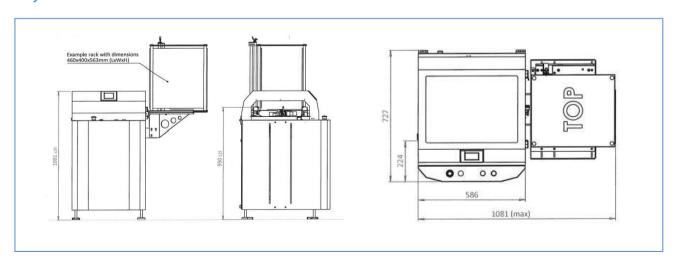
FIFO/LIFO buffer

This module usesa lifting platform to place PCB into the magazine. The capacity of the buffer depends on the total high of the circuit board, normally 50 positions at pitch 10mm.

FIFO/LIFO and pass through are selectable operation modes. Also used as G/B PCB separator.



Layout Module



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FLO SERIES GENERAL FEATURES

TRANSPORT	
Height:	950 mm +/- 25 mm
Width:	Min. 90 mm – Max 350 mm
PCB edge space:	Min. 3 mm
Transfer direction:	Left to right
Operating side:	Front of the machine
Fixed Rail:	Front of the machine
Interface:	Std. or Extd. SMEMA Opt Fuji, Panasonic, Sanyo, Siemens, SMPI, Special
SMEMA cable length:	3 m

PANEL DIMENSION	
Length:	Min. 90 mm – Max 450 mm
Width:	Min. 90 mm – Max 350 mm
Thickness:	From 0.8 mm to 4.0 mm
Component clearance:	Top: 40 mm Bottom: 20 mm
PCB max weight:	1 Kg
Max dimension of the rack:	L 460 x W 440 x H 570 (mm) External Measurements

VARIOUS:

CE safety compliant

• PLC microprocessor driven system

Mechanical keyboard or LCD display

 Single piece aluminum rails, proprietary design POWER SUPPLY: 230V 1Ph+N+G 50Hz

CURRENT: 2 Ampere

AIR SUPPLY: 0.6 Mpa

WEIGHT: 90 Kg

DIMENSION 1.081x727x1.091mm (Rack Homing)

LXWXH:

COLOR: RAL 7035

TRASPARENT COVER: STANDARD (NO ESD)

All modules are ESD compliant and CE marked, each module has an independent control system. Technical specification may change without any advanced notice.



Seica Automation s.r.l